



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	HCS12
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	96КВ (96К х 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.72V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TFQFN Exposed Pad
Supplier Device Package	48-QFN-EP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12p96mftr

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



	8.2.3	CAN System	254
8.3	Memor	y Map and Register Definition	254
	8.3.1	Module Memory Map	254
	8.3.2	Register Descriptions	256
	8.3.3	Programmer's Model of Message Storage	275
8.4	Functio	nal Description	285
	8.4.1	General	285
	8.4.2	Message Storage	286
	8.4.3	Identifier Acceptance Filter	289
	8.4.4	Modes of Operation	295
	8.4.5	Low-Power Options	297
	8.4.6	Reset Initialization	301
	8.4.7	Interrupts	301
8.5	Initializ	ation/Application Information	303
	8.5.1	MSCAN initialization	303
	8.5.2	Bus-Off Recovery	303

Chapter 9 Analog-to-Digital Converter (ADC12B10C)

9.1	Introduction	
	9.1.1 Features	
	9.1.2 Modes of Operation	
	9.1.3 Block Diagram	
9.2	Signal Description	
	9.2.1 Detailed Signal Descriptions	
9.3	Memory Map and Register Definition	
	9.3.1 Module Memory Map	
	9.3.2 Register Descriptions	
9.4	Functional Description	
	9.4.1 Analog Sub-Block	
	9.4.2 Digital Sub-Block	
9.5	Resets	
9.6	Interrupts	

Chapter 10

Pulse-Width Modulator (PWM8B6CV1) Block Description

10.1	Introduction	329
	10.1.1 Features	329
	10.1.2 Modes of Operation	329
	10.1.3 Block Diagram	330
10.2	External Signal Description	330
	10.2.1 PWM5 — Pulse Width Modulator Channel 5 Pin	330
	10.2.2 PWM4 — Pulse Width Modulator Channel 4 Pin	330
	10.2.3 PWM3 — Pulse Width Modulator Channel 3 Pin 3	330

Device Overview MC9S12P-Family

Р	ackage P	in		Function		Power	Internal Pull Resistor		Description
QFP 80	LQFP 64	QFN 48	Pin	2nd Func.	3rd Func.	Supply	CTRL	Reset State	Description
53	41	30	PAD02	AN02		VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
54	42	31	PAD03	AN03	_	VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
55	43	32	PAD04	AN04		VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
56	44	33	PAD05	AN05		VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
57	45	34	PAD06	AN06		VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
58	46	35	PAD07	AN07		VDDA	PER1AD	Disabled	Port AD I/O, analog input of ATD
59	47	36	VDDA	—	—	—	—	—	_
60	48	36	VRH ⁽²⁾	_	_	_	_	_	_
61	49	37	VRL ⁽³⁾	_		_			_
62	49	37	VSSA	_	_	_	_	_	_
63	50	38	PS0	RXD		VDDX	PERS/PPSS	Up	Port S I/O, RXD of SCI
64	51	39	PS1	TXD	—	VDDX	PERS/PPSS	Up	Port S I/O, TXD of SCI
65	52	-	PS2		_	VDDX	PERS/PPSS	Up	Port S I/O
66	53	-	PS3		—	VDDX	PERS/PPSS	Up	Port S I/O
67	54	40	TEST	_		N.A.	RESET pin	DOWN	Test input
68	-	-	PJ7	KWJ7	—	VDDX	PERJ/PPSJ	Up	Port J I/O, interrupt
69	-	-	PJ6	KWJ6	—	VDDX	PERJ/PPSJ	Up	Port J I/O, interrupt
70	55	41	PM5	SCK		VDDX	PERM/PPSM	Disabled	Port M I/O, MISO of SPI

36

S12P-Family Reference Manual, Rev. 1.13



Table 2-37. DDRP Register Field Descriptions (continued)

Field	Description
5 DDRP	 Port P data direction— This bit determines whether the associated pin is an input or output. The PWM forces the I/O state to be an output for an enabled channel. If the emergency shut-down feature is enabled this pin is an input. In this case the data direction bit will not change. 1 Associated pin is configured as output 0 Associated pin is configured as input
4-0 DDRP	 Port P data direction— This bit determines whether the associated pin is an input or output. The PWM forces the I/O state to be an output for an enabled channel. In this case the data direction bit will not change. 1 Associated pin is configured as output 0 Associated pin is configured as input

2.3.43 Port P Reduced Drive Register (RDRP)

Access: User read/write⁽¹⁾ Address 0x025B 2 7 6 5 4 3 1 0 0 R RDRP7 RDRP5 RDRP4 RDRP3 RDRP2 RDRP1 RDRP0 W 0 0 0 0 0 0 0 0 Reset

Figure 2-41. Port P Reduced Drive Register (RDRP)

1. Read: Anytime

Write: Anytime

Table 2-38. RDRP Register Field Descriptions

Field	Description	
7,5-0 RDRP	Port P reduced drive —Select reduced drive for output pin This bit configures the drive strength of the associated output pin as either full or reduced. If a pin is used as input this bit has no effect. The reduced drive function is independent of which function is being used on a particular pin.	
	0 Full drive strength enabled	



3.1.2 Overview

The S12PMMC connects the CPU12's and the S12SBDM's bus interfaces to the MCU's on-chip ressources (memories and peripherals). It arbitrates the bus accesses and detemines all of the MCU's memory maps. Furthermore, the S12PMMC is responsible for constraining memory accesses on secured devices and for selecting the MCU's functional mode.

3.1.3 Features

The main features of this block are:

- Paging capability to support a global 256 KByte memory address space
- Bus arbitration between the masters CPU12, S12SBDM to different resources.
- MCU operation mode control
- MCU security control
- Separate memory map schemes for each master CPU12, S12SBDM
- Generation of system reset when CPU12 accesses an unimplemented address (i.e., an address which does not belong to any of the on-chip modules) in single-chip modes

3.1.4 Modes of Operation

The S12PMMC selects the MCU's functional mode. It also determines the devices behavior in secured and unsecured state.

3.1.4.1 Functional Modes

Two funtional modes are implementes on devices of the S12I product family:

- Normal Single Chip (NS) The mode used for running applications.
- Special Single Chip Mode (SS) A debug mode which causes the device to enter BDM Active Mode after each reset. Peripherals may also provide special debug features in this mode.

3.1.4.2 Security

S12I devives can be secured to prohibit external access to the on-chip P-Flash. The S12PMMC module determines the access permissions to the on-chip memories in secured and unsecured state.

3.1.5 Block Diagram

Figure 3-1 shows a block diagram of the S12PMMC.

5.4.7 Serial Interface Hardware Handshake Protocol

BDM commands that require CPU execution are ultimately treated at the MCU bus rate. Since the BDM clock source can be modified when changing the settings for the VCO frequency (CPMUSYNR), it is very helpful to provide a handshake protocol in which the host could determine when an issued command is executed by the CPU. The BDM clock frequency is always VCO frequency divided by 8. The alternative is to always wait the amount of time equal to the appropriate number of cycles at the slowest possible rate the clock could be running. This sub-section will describe the hardware handshake protocol.

The hardware handshake protocol signals to the host controller when an issued command was successfully executed by the target. This protocol is implemented by a 16 serial clock cycle low pulse followed by a brief speedup pulse in the BKGD pin. This pulse is generated by the target MCU when a command, issued by the host, has been successfully executed (see Figure 5-10). This pulse is referred to as the ACK pulse. After the ACK pulse has finished: the host can start the bit retrieval if the last issued command was a read command, or start a new command if the last command was a write command or a control command (BACKGROUND, GO, GO_UNTIL or TRACE1). The ACK pulse is not issued earlier than 32 serial clock cycles after the BDM command was issued. The end of the BDM command is assumed to be the 16th tick of the last bit. This minimum delay assures enough time for the host to perceive the ACK pulse. Note also that, there is no upper limit for the delay between the command and the related ACK pulse, since the command execution depends upon the CPU bus, which in some cases could be very slow due to long accesses taking place. This protocol allows a great flexibility for the POD designers, since it does not rely on any accurate time measurement or short response time to any event in the serial communication.





NOTE

If the ACK pulse was issued by the target, the host assumes the previous command was executed. If the CPU enters wait or stop prior to executing a hardware command, the ACK pulse will not be issued meaning that the BDM command was not executed. After entering wait or stop mode, the BDM command is no longer pending.



a forced match, a state sequencer transition can occur immediately on a successful match of system busses and comparator registers. Whilst tagging, at a comparator match, the instruction opcode is tagged and only if the instruction reaches the execution stage of the instruction queue can a state sequencer transition occur. In the case of a transition to Final State, bus tracing is triggered and/or a breakpoint can be generated.

A state sequencer transition to final state (with associated breakpoint, if enabled) can be initiated by writing to the TRIG bit in the DBGC1 control register.

The trace buffer is visible through a 2-byte window in the register address map and must be read out using standard 16-bit word reads.



Figure 6-23. DBG Overview

6.4.2 Comparator Modes

The DBG contains three comparators, A, B and C. Each comparator compares the system address bus with the address stored in DBGXAH, DBGXAM, and DBGXAL. Furthermore, comparator A also compares the data buses to the data stored in DBGADH, DBGADL and allows masking of individual data bus bits.

All comparators are disabled in BDM and during BDM accesses.

The comparator match control logic (see Figure 6-23) configures comparators to monitor the buses for an exact address or an address range, whereby either an access inside or outside the specified range generates a match condition. The comparator configuration is controlled by the control register contents and the range control by the DBGC2 contents.

A match can initiate a transition to another state sequencer state (see 6.4.4"). The comparator control register also allows the type of access to be included in the comparison through the use of the RWE, RW, SZE, and SZ bits. The RWE bit controls whether read or write comparison is enabled for the associated comparator and the RW bit selects either a read or write access for a valid match. Similarly the SZE and



6.5.2 Scenario 1

A trigger is generated if a given sequence of 3 code events is executed.

Figure 6-27. Scenario 1



Scenario 1 is possible with S12SDBGV1 SCR encoding

6.5.3 Scenario 2

A trigger is generated if a given sequence of 2 code events is executed.

Figure 6-28. Scenario 2a



A trigger is generated if a given sequence of 2 code events is executed, whereby the first event is entry into a range (COMPA,COMPB configured for range mode). M1 is disabled in range modes.



A trigger is generated if a given sequence of 2 code events is executed, whereby the second event is entry into a range (COMPA,COMPB configured for range mode)





All 3 scenarios 2a,2b,2c are possible with the S12SDBGV1 SCR encoding

S12P-Family Reference Manual, Rev. 1.13





Figure 7-19. Waveform selected on API_EXTCLK pin (APIEA=1, APIFE=1)

Field	Description
3-2 TSTAT[1:0]	Transmitter Status Bits — The values of the error counters control the actual CAN bus status of the MSCAN.As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate transmitter relatedCAN bus status of the MSCAN. The coding for the bits TSTAT1, TSTAT0 is:00 TxOK: 0 ≤ transmit error counter ≤ 9601 TxWRN: 96 < transmit error counter ≤ 127
1 OVRIF	Overrun Interrupt Flag — This flag is set when a data overrun condition occurs. If not masked, an error interrupt is pending while this flag is set. 0 No data overrun condition 1 A data overrun detected
0 RXF ⁽²⁾	Receive Buffer Full Flag — RXF is set by the MSCAN when a new message is shifted in the receiver FIFO. This flag indicates whether the shifted buffer is loaded with a correctly received message (matching identifier, matching cyclic redundancy code (CRC) and no other errors detected). After the CPU has read that message from the RxFG buffer in the receiver FIFO, the RXF flag must be cleared to release the buffer. A set RXF flag prohibits the shifting of the next FIFO entry into the foreground buffer (RxFG). If not masked, a receive interrupt is pending while this flag is set. 0 No new message available within the RxFG 1 The receiver FIFO is not empty. A new message is available in the RxFG

Table 8-11. CANRFLG Register Field Descriptions (continued)

1. Redundant Information for the most critical CAN bus status which is "bus-off". This only occurs if the Tx error counter exceeds a number of 255 errors. Bus-off affects the receiver state. As soon as the transmitter leaves its bus-off state the receiver state skips to RxOK too. Refer also to TSTAT[1:0] coding in this register.

2. To ensure data integrity, do not read the receive buffer registers while the RXF flag is cleared. For MCUs with dual CPUs, reading the receive buffer registers while the RXF flag is cleared may result in a CPU fault condition.

8.3.2.6 MSCAN Receiver Interrupt Enable Register (CANRIER)

This register contains the interrupt enable bits for the interrupt flags described in the CANRFLG register.



R W	WUPIE	CSCIE	RSTATE1	RSTATE0	TSTATE1	TSTATE0	OVRIE	RXFIE
Reset:	0	0	0	0	0	0	0	0

Figure 8-9. MSCAN Receiver Interrupt Enable Register (CANRIER)

1. Read: Anytime

Write: Anytime when not in initialization mode

NOTE

The CANRIER register is held in the reset state when the initialization mode is active (INITRQ=1 and INITAK=1). This register is writable when not in initialization mode (INITRQ=0 and INITAK=0).

The RSTATE[1:0], TSTATE[1:0] bits are not affected by initialization mode.



1. Read: Anytime

Write: Anytime when not in initialization mode

NOTE

The CANTIER register is held in the reset state when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable when not in initialization mode (INITRQ = 0 and INITAK = 0).

Table 8-14. CANTIER Register Field Descriptions

Field	Description
2-0 TXEIE[2:0]	 Transmitter Empty Interrupt Enable 0 No interrupt request is generated from this event. 1 A transmitter empty (transmit buffer available for transmission) event causes a transmitter empty interrupt request.

8.3.2.9 MSCAN Transmitter Message Abort Request Register (CANTARQ)

The CANTARQ register allows abort request of queued messages as described below.

Module Base + 0x0008 Access: User read/write⁽¹⁾

	7	6	5	4	3	2	1	0
R	0	0	0	0	0			
W						ADINQZ	ADIRQI	ABINGU
Reset:	0	0	0	0	0	0	0	0
		= Unimplen	nented					

Figure 8-12. MSCAN Transmitter Message Abort Request Register (CANTARQ)

1. Read: Anytime

Write: Anytime when not in initialization mode

NOTE

The CANTARQ register is held in the reset state when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable when not in initialization mode (INITRQ = 0 and INITAK = 0).

Table 8-15. CANTARQ Register Field Descriptions

Field	Description
2-0 ABTRQ[2:0]	 Abort Request — The CPU sets the ABTRQx bit to request that a scheduled message buffer (TXEx = 0) be aborted. The MSCAN grants the request if the message has not already started transmission, or if the transmission is not successful (lost arbitration or error). When a message is aborted, the associated TXE (see Section 8.3.2.7, "MSCAN Transmitter Flag Register (CANTFLG)") and abort acknowledge flags (ABTAK, see Section 8.3.2.10, "MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)") are set and a transmit interrupt occurs if enabled. The CPU cannot reset ABTRQx. ABTRQx is reset whenever the associated TXE flag is set. 0 No abort request 1 Abort request pending



Freescale's Scalable Controller Area Network (S12MSCANV3)

1. Read: Anytime when TXEx flag is set (see Section 8.3.2.7, "MSCAN Transmitter Flag Register (CANTFLG)") and the corresponding transmit buffer is selected in CANTBSEL (see Section 8.3.2.11, "MSCAN Transmit Buffer Selection Register (CANTBSEL)") Write: Unimplemented

8.4 **Functional Description**

8.4.1 General

This section provides a complete functional description of the MSCAN.



8.4.2 Message Storage



Figure 8-39. User Model for Message Buffer Organization

The MSCAN facilitates a sophisticated message storage system which addresses the requirements of a broad range of network applications.

8.4.2.1 Message Transmit Background

Modern application layer software is built upon two fundamental assumptions:





9.4.1 Analog Sub-Block

The analog sub-block contains all analog electronics required to perform a single conversion. Separate power supplies V_{DDA} and V_{SSA} allow to isolate noise of other MCU circuitry from the analog sub-block.

9.4.1.1 Sample and Hold Machine

The Sample and Hold (S/H) Machine accepts analog signals from the external world and stores them as capacitor charge on a storage node.

During the sample process the analog input connects directly to the storage node.

The input analog signals are unipolar and must fall within the potential range of V_{SSA} to V_{DDA} .

During the hold process the analog input is disconnected from the storage node.

9.4.1.2 Analog Input Multiplexer

The analog input multiplexer connects one of the 10 external analog input channels to the sample and hold machine.

9.4.1.3 Analog-to-Digital (A/D) Machine

The A/D Machine performs analog to digital conversions. The resolution is program selectable at either 8 or 10 or 12 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the stored analog sample potential with a series of digitally generated analog potentials. By following a binary search algorithm, the A/D machine locates the approximating potential that is nearest to the sampled potential.

When not converting the A/D machine is automatically powered down.

Only analog input signals within the potential range of V_{RL} to V_{RH} (A/D reference potentials) will result in a non-railed digital output code.

9.4.2 Digital Sub-Block

This subsection explains some of the digital features in more detail. See Section 9.3.2, "Register Descriptions" for all details.

9.4.2.1 External Trigger Input

The external trigger feature allows the user to synchronize ATD conversions to the external environment events rather than relying on software to signal the ATD module when ATD conversions are to take place. The external trigger signal (out of reset ATD channel 9, configurable in ATDCTL1) is programmable to





Figure 10-40. PWM 16-Bit Mode

When using the 16-bit concatenated mode, the clock source is determined by the low-order 8-bit channel clock select control bits. That is channel 5 when channels 4 and 5 are concatenated, channel 3 when channels 2 and 3 are concatenated, and channel 1 when channels 0 and 1 are concatenated. The resulting PWM is output to the pins of the corresponding low-order 8-bit channel as also shown in Figure 10-40. The polarity of the resulting PWM output is controlled by the PPOLx bit of the corresponding low-order 8-bit channel as well.

After concatenated mode is enabled (CONxx bits set in PWMCTL register), enabling/disabling the corresponding 16-bit PWM channel is controlled by the low-order PWMEx bit. In this case, the high-order bytes PWMEx bits have no effect and their corresponding PWM output is disabled.

In concatenated mode, writes to the 16-bit counter by using a 16-bit access or writes to either the low or high-order byte of the counter will reset the 16-bit counter. Reads of the 16-bit counter must be made by 16-bit access to maintain data coherency.

Either left aligned or center aligned output mode can be used in concatenated mode and is controlled by the low-order CAEx bit. The high-order CAEx bit has no effect.



Table 11-2. SCIBDH and SCIBDL Field Descriptions
--

Field	Description
7 IREN	 Infrared Enable Bit — This bit enables/disables the infrared modulation/demodulation submodule. 0 IR disabled 1 IR enabled
6:5 TNP[1:0]	Transmitter Narrow Pulse Bits — These bits enable whether the SCI transmits a 1/16, 3/16, 1/32 or 1/4 narrow pulse. See Table 11-3.
4:0 7:0 SBR[12:0]	 SCI Baud Rate Bits — The baud rate for the SCI is determined by the bits in this register. The baud rate is calculated two different ways depending on the state of the IREN bit. The formulas for calculating the baud rate are: When IREN = 0 then, SCI baud rate = SCI bus clock / (16 x SBR[12:0]) When IREN = 1 then, SCI baud rate = SCI bus clock / (32 x SBR[12:1]) Note: The baud rate generator is disabled after reset and not started until the TE bit or the RE bit is set for the first time. The baud rate generator is disabled when (SBR[12:0] = 0 and IREN = 0) or (SBR[12:1] = 0 and IREN = 1). Note: Writing to SCIBDH has no effect without writing to SCIBDL, because writing to SCIBDH puts the data in a temporary location until SCIBDL is written to.

Table 11-3. IRSCI Transmit Pulse Width

TNP[1:0]	Narrow Pulse Width
11	1/4
10	1/32
01	1/16
00	3/16

11.3.2.2 SCI Control Register 1 (SCICR1)

_	7	6	5	4	3	2	1	0
R W	LOOPS	SCISWAI	RSRC	Μ	WAKE	ILT	PE	PT
Reset	0	0	0	0	0	0	0	0

Figure 11-5. SCI Control Register 1 (SCICR1)

Read: Anytime, if AMAP = 0.

Write: Anytime, if AMAP = 0.

NOTE

This register is only visible in the memory map if AMAP = 0 (reset condition).



eripheral Interface (S12SPIV5)

The main element of the SPI system is the SPI data register. The n-bit¹ data register in the master and the n-bit¹ data register in the slave are linked by the MOSI and MISO pins to form a distributed 2n-bit¹ register. When a data transfer operation is performed, this 2n-bit¹ register is serially shifted n¹ bit positions by the S-clock from the master, so data is exchanged between the master and the slave. Data written to the master SPI data register becomes the output data for the slave, and data read from the master SPI data register operation is the input data from the slave.

A read of SPISR with SPTEF = 1 followed by a write to SPIDR puts data into the transmit data register. When a transfer is complete and SPIF is cleared, received data is moved into the receive data register. This data register acts as the SPI receive data register for reads and as the SPI transmit data register for writes. A common SPI data register address is shared for reading data from the read data buffer and for writing data to the transmit data register.

The clock phase control bit (CPHA) and a clock polarity control bit (CPOL) in the SPI control register 1 (SPICR1) select one of four possible clock formats to be used by the SPI system. The CPOL bit simply selects a non-inverted or inverted clock. The CPHA bit is used to accommodate two fundamentally different protocols by sampling data on odd numbered SCK edges or on even numbered SCK edges (see Section 12.4.3, "Transmission Formats").

The SPI can be configured to operate as a master or as a slave. When the MSTR bit in SPI control register 1 is set, master mode is selected, when the MSTR bit is clear, slave mode is selected.

NOTE

A change of CPOL or MSTR bit while there is a received byte pending in the receive shift register will destroy the received byte and must be avoided.

12.4.1 Master Mode

The SPI operates in master mode when the MSTR bit is set. Only a master SPI module can initiate transmissions. A transmission begins by writing to the master SPI data register. If the shift register is empty, data immediately transfers to the shift register. Data begins shifting out on the MOSI pin under the control of the serial clock.

Serial clock

The SPR2, SPR1, and SPR0 baud rate selection bits, in conjunction with the SPPR2, SPPR1, and SPPR0 baud rate preselection bits in the SPI baud rate register, control the baud rate generator and determine the speed of the transmission. The SCK pin is the SPI clock output. Through the SCK pin, the baud rate generator of the master controls the shift register of the slave peripheral.

• MOSI, MISO pin

In master mode, the function of the serial data output pin (MOSI) and the serial data input pin (MISO) is determined by the SPC0 and BIDIROE control bits.

• <u>SS</u> pin

If MODFEN and SSOE are set, the \overline{SS} pin is configured as slave select output. The \overline{SS} output becomes low during each transmission and is high when the SPI is in idle state.

If MODFEN is set and SSOE is cleared, the \overline{SS} pin is configured as input for detecting mode fault error. If the \overline{SS} input becomes low this indicates a mode fault error where another master tries to 1. n depends on the selected transfer width, please refer to Section 12.3.2.2, "SPI Control Register 2 (SPICR2)



14.3.2.15 16-Bit Pulse Accumulator Control Register (PACTL)

Module Base + 0x0020

	7	6	5	4	3	2	1	0
R W	0	PAEN	PAMOD	PEDGE	CLK1	CLK0	PAOVI	PAI
Reset	0	0	0	0	0	0	0	0
		Unimplemente	ed or Reserved					

Figure 14-24. 16-Bit Pulse Accumulator Control Register (PACTL)

When PAEN is set, the PACT is enabled. The PACT shares the input pin with IOC7.

Read: Any time

Write: Any time

Field	Description
6 PAEN	 Pulse Accumulator System Enable — PAEN is independent from TEN. With timer disabled, the pulse accumulator can function unless pulse accumulator is disabled. 0 16-Bit Pulse Accumulator system disabled. 1 Pulse Accumulator system enabled.
5 PAMOD	 Pulse Accumulator Mode — This bit is active only when the Pulse Accumulator is enabled (PAEN = 1). See Table 14-18. 0 Event counter mode. 1 Gated time accumulation mode.
4 PEDGE	 Pulse Accumulator Edge Control — This bit is active only when the Pulse Accumulator is enabled (PAEN = 1). For PAMOD bit = 0 (event counter mode). See Table 14-18. 0 Falling edges on IOC7 pin cause the count to be incremented. 1 Rising edges on IOC7 pin cause the count to be incremented. For PAMOD bit = 1 (gated time accumulation mode). 0 IOC7 input pin high enables M (bus clock) divided by 64 clock to Pulse Accumulator and the trailing falling edge on IOC7 sets the PAIF flag. 1 IOC7 input pin low enables M (bus clock) divided by 64 clock to Pulse Accumulator and the trailing rising edge on IOC7 sets the PAIF flag.
3:2 CLK[1:0]	Clock Select Bits — Refer to Table 14-19.
1 PAOVI	Pulse Accumulator Overflow Interrupt Enable 0 Interrupt inhibited. 1 Interrupt requested if PAOVF is set.
0 PAI	Pulse Accumulator Input Interrupt Enable 0 Interrupt inhibited. 1 Interrupt requested if PAIF is set.

Table 14-17. PACTL Field Descriptions



Table 14-20. PAFLG Field Descriptions

Field	Description
1 PAOVF	Pulse Accumulator Overflow Flag — Set when the 16-bit pulse accumulator overflows from 0xFFFF to 0x0000. Clearing this bit requires writing a one to this bit in the PAFLG register while TEN bit of TSCR1 or PAEN bit of PACTL register is set to one.
0 PAIF	Pulse Accumulator Input edge Flag — Set when the selected edge is detected at the IOC7 input pin. In event mode the event edge triggers PAIF and in gated time accumulation mode the trailing edge of the gate signal at the IOC7 input pin triggers PAIF.
	Clearing this bit requires writing a one to this bit in the PAFLG register while TEN bit of TSCR1 or PAEN bit of PACTL register is set to one. Any access to the PACNT register will clear all the flags in this register when TFFCA bit in register TSCR(0x0006) is set.

14.3.2.17 Pulse Accumulators Count Registers (PACNT)





Figure 14-27. Pulse Accumulator Count Register Low (PACNTL)

Read: Anytime

Write: Anytime

These registers contain the number of active input edges on its input pin since the last reset.

When PACNT overflows from 0xFFFF to 0x0000, the Interrupt flag PAOVF in PAFLG (0x0021) is set.

Full count register access should take place in one clock cycle. A separate read/write for high byte and low byte will give a different result than accessing them as a word.

NOTE

Reading the pulse accumulator counter registers immediately after an active edge on the pulse accumulator input pin may miss the last count because the input has to be synchronized with the bus clock first.



Table A-7. 5-V I/O Characteristics

Conditions are 4.5 V < V_{DD35} < 5.5 V junction temperature from -40°C to +150°C, unless otherwise noted I/O Characteristics for all I/O pins except EXTAL, XTAL,TEST and supply pins.								
Num	С	Rating	Symbol	Min	Тур	Max	Unit	
1	Р	Input high voltage	V _{IH}	0.65*V _{DD35}		—	V	
	Т	Input high voltage	V _{IH}	—	_	V _{DD35} + 0.3	V	
2	Р	Input low voltage	V _{IL}	—	_	0.35*V _{DD35}	V	
	Т	Input low voltage	V _{IL}	V _{SS35} -0.3	_	—	V	
3	С	Input hysteresis	VHYS		250	—	mV	
4	P C C	Input leakage current (pins in high impedance input mode) ⁽¹⁾ $V_{in} = V_{DD35}$ or V_{SS35} M temperature range -40° C to $+150^{\circ}$ C V temperature range -40° C to $+125^{\circ}$ C C temperature range -40° C to $+105^{\circ}$ C	l _{in}	-1.00 -0.75 -0.50	 	1.00 0.75 0.50	μA	
5	С	Output high voltage (pins in output mode) Partial drive $I_{OH} = -2 \text{ mA}$	V _{OH}	V _{DD35} – 0.8	_	_	V	
6	Ρ	Output high voltage (pins in output mode) Full drive I _{OH} = -10 mA	V _{OH}	V _{DD35} – 0.8	_	_	V	
7	С	Output low voltage (pins in output mode) Partial drive I _{OL} = +2 mA	V _{OL}	_	—	0.8	V	
8	Ρ	Output low voltage (pins in output mode) Full drive I _{OL} = +10 mA	V _{OL}	—	—	0.8	V	
9	Ρ	Internal pull up resistance V _{IH} min > input voltage > V _{IL} max	R _{PUL}	25	—	50	KΩ	
10	Ρ	Internal pull down resistance V _{IH} min > input voltage > V _{IL} max	R _{PDH}	25	—	50	KΩ	
11	D	Input capacitance	C _{in}	—	6	—	pF	
12	Т	Injection current ⁽²⁾ Single pin limit Total device Limit, sum of all injected currents	I _{ICS} I _{ICP}	-2.5 -25	—	2.5 25	mA	
13	Ρ	Port J, P interrupt input pulse filtered (STOP) ⁽³⁾	t _{PULSE}	_	_	3	μs	
14	Ρ	Port J, P interrupt input pulse passed (STOP) ³	t _{PULSE}	10			μs	
15	D	Port J, P interrupt input pulse filtered (STOP)	t _{PULSE}	_		3	tcyc	
16	D	Port J, P interrupt input pulse passed ($\overline{\text{STOP}}$)	t _{PULSE}	4		_	tcyc	

 17
 D
 IRQ pulse width, edge-sensitive mode (STOP)
 PW_{IRQ}

1. Maximum leakage current occurs at maximum operating temperature. Current decreases by approximately one-half for each 8°C to 12 C in the temperature range from 50°C to 125°C.

1

2. Refer to Section A.1.4, "Current Injection" for more details

3. Parameter only applies in stop or pseudo stop mode.

tcyc



How to Reach Us:

USA/Europe/Locations not listed:

Freescale Semiconductor Literature Distribution P.O. Box 5405, Denver, Colorado 80217 1-800-521-6274 or 480-768-2130

Japan:

Freescale Semiconductor Japan Ltd. SPS, Technical Information Center 3-20-1, Minami-Azabu Minato-ku Tokyo 106-8573, Japan 81-3-3440-3569

Asia/Pacific:

Freescale Semiconductor H.K. Ltd. 2 Dai King Street Tai Po Industrial Estate Tai Po, N.T. Hong Kong 852-26668334

Learn More:

For more information about Freescale Semiconductor products, please visit http://www.freescale.com Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale[™] and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners. © Freescale Semiconductor, Inc. 2010